

1 **DOUBLE SIDED CHIP PACKAGE**

2 **ABSTRACT**

3 A double sided chip package is disclosed. The package includes a LOC leadframe having
4 a plurality of leads. Each lead is outwardly divided into a supporting portion extended
5 between a bottom chip and a upper chip for supporting both chips, an inner connecting
6 portion sealed by a package body for electrically connecting the bottom chip and the
7 upper chip to the LOC leadframe by wire-bonding, and an outer portion exposed from the
8 package body. So the double sided chip package has the benefits of a less warping, a
9 stronger lead bonding, and a well-balancing molding flow.

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